GLSVLSI 2025

June 30th -July 2nd 2025, New Orleans, LA, USA

http://www.glsvlsi.org/
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The 35th edition of Great Lakes Symposium on VLSI (GLSVLSI) will be held as an in-person conference. Original, unpublished papers describing research in the general areas of VLSI and hardware design are solicited. Please visit http://www.glsvlsi.org/ for more information.

Program Tracks:

- VLSI Circuits and Design: ASIC and FPGA design, microprocessors/micro-architectures, embedded
 processors, high-speed/low-power circuits, analog/digital/mixed-signal systems, NoC, SoC, IoT,
 interconnects, memories, bio-inspired and neuromorphic circuits and systems, BioMEMs, lab-on-achip, biosensors, CAD tools for biology and biomedical systems, implantable and wearable devices,
 machine-learning for VLSI design and optimization
- **IoT and Smart Systems:** circuits, computing, processing, and design of IoT and smart systems such as smart cities, smart healthcare, smart transportation, smart grid etc.; cyber-physical systems, edge computing, machine learning for IoT, TinyML.
- Computer-Aided Design (CAD): hardware/software co-design, high-level synthesis, logic synthesis, simulation and formal verification, layout, design for manufacturing, algorithms and complexity analysis, physical design (placement, route, CTS), static timing analysis, signal and power integrity, machine learning for CAD and EDA design.
- Testing, Reliability, Fault-Tolerance: digital/analog/mixed-signal testing, reliability, robustness, static/dynamic defect- and fault-recoverability, variation-aware design, learning-assisted testing.
- Emerging Computing & Post-CMOS Technologies: nanotechnology, quantum computing, approximate and stochastic computing, sensor and sensor networks, post CMOS VLSI.
- Hardware Security: trusted IC, IP protection, hardware security primitives, reverse engineering, hardware Trojans, side-channel analysis, CPS/IoT security, machine learning for HW security.
- VLSI for Machine Learning and Artificial Intelligence: hardware accelerators for machine learning, novel architectures for deep learning, brain-inspired computing, big data computing, reinforcement learning, cloud computing for Internet-of-Things (IoT) devices.

Microelectronic System Education Workshop:

A one-day co-located workshop will cover the following topics: pedagogical innovations using a wide range of technologies such as ASIC, FPGA, multicore, GPU, TPU, educational techniques including novel curricula and laboratories, assessment methods, distance learning, textbooks, and design projects, industry and academic collaborative programs and teaching.

Paper submission deadline: March 17, 2025 (11:59 pm EST)

Acceptance Notification: April 30, 2025 Camera-Ready: May 15, 2025

Paper Submission: Authors are invited to submit full-length 6-page, original, unpublished papers along with an abstract of at most 200 words. Submissions exceeding 6 pages are permitted but must not exceed 8 pages in total. Each additional page beyond 6 will incur an extra fee upon acceptance for publication. To enable blind review, the author list should be omitted from the main document. Previously published papers or papers currently under review for other conferences/journals should NOT be submitted and will not be considered. Electronic submission in PDF format to the https://easychair.org/conferences/?conf=glsv/si25 website is required. Author and contact information (name, affiliation, mailing address, telephone, fax, e-mail) must be entered during the submission process.

Paper Format: Submissions should be in camera-ready two-column format, following the ACM proceedings specifications located at: ACM Template and the classification system detailed at: ACM Proceedings Template - Overleaf. For Overleaf users, please find the following template: ACM Proceedings Template - Overleaf. For LaTeX users, please find the following ZIP file: acmart-primary.zip. For Word users, please find the following template: interim-layout.docx.

Paper Publication and Presenter Registration: Papers will be accepted for regular or poster presentation at the symposium. Every accepted paper MUST have at least one author registered to the symposium by the time the camera-ready paper is submitted; at least one of the authors is also expected to attend the symposium and present the paper.

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